DMA20601

Silicon PNP epitaxial planar type

For general amplification

■ Features

- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

■ Basic Part Number

Dual DSA2001 (Individual)

Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	-60	V	
Collector-emitter voltage (Base open)	V _{CEO}	-50	V	
Emitter-base voltage (Collector open)	V_{EBO}	-7	V	
Collector current	I_{C}	-100	mA	
Peak collector current	I_{CP}	-200	mA	
Total power dissipation	P _T	300	mW	
Junction temperature	T_j	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	

■ Package

Code

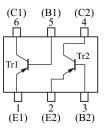
Mini6-G4-B

• Pin Name

1: Emitter (Tr1) 4: Collector (Tr2) 2: Emitter (Tr2) 5: Base (Tr1) 3: Base (Tr2) 6: Collector (Tr1)

■ Marking Symbol: B2

■ Internal Connection



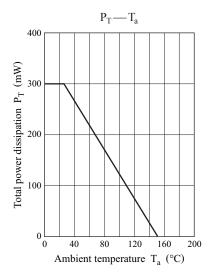
■ Electrical Characteristics $T_a = 25$ °C±3°C

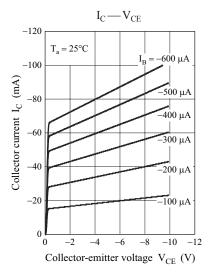
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = -10 \mu \text{A}, I_{\rm E} = 0$	-60			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = -2 \text{ mA}, I_B = 0$	-50			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = -10 \mu A, I_C = 0$	-7			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{\rm CB} = -20 \text{ V}, I_{\rm E} = 0$			-0.1	μА
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = -10 \text{ V}, I_{B} = 0$			-100	μА
Forward current transfer ratio	h_{FE}	$V_{CE} = -10 \text{ V}, I_{C} = -2 \text{ mA}$	210		460	_
h _{FE} ratio *	h _{FE} (Small/Large)	$V_{CE} = -10 \text{ V}, I_{C} = -2 \text{ mA}$	0.50	0.99		_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = -100 \text{ mA}, I_B = -10 \text{ mA}$		-0.2	-0.5	V
Transition frequency	f_T	$V_{CE} = -10 \text{ V}, I_{C} = -2 \text{ mA}$		150		MHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		2		pF

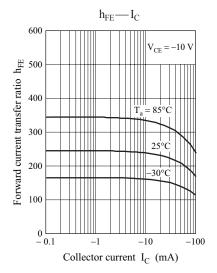
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

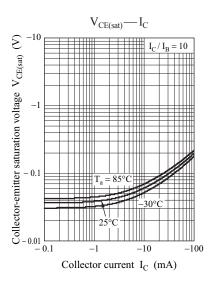
2. *: Ratio between 2 elements

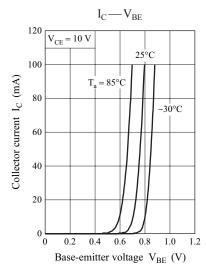
DMA20601 Panasonic

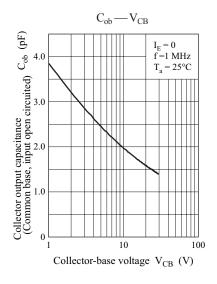


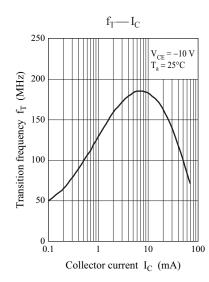






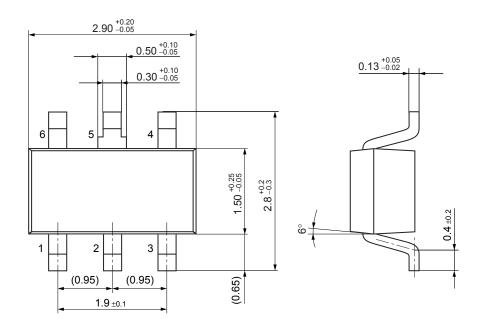


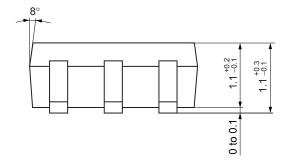




2 ZJJ00535BED

Mini6-G4-B Unit: mm





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